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FACSIMILE COVER SHEET

Date: June 16, 2003	Client & Matter Number : 015114-052310US	No. Pages (including this one): 2
To: Examiner Nitin Parekh Art Unit 2811 U.S. Patent and Trademark Office	At Fax Number: 1 (703) 308-7722, 4	Confirmation Phone Number:

From :

Melvin D. Chan

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JUN 16 2003

(x521)

Message:

TECHNOLOGY CENTER 2800

Re: U.S. Patent Application 09/517,345 for
METHOD AND STRUCTURE FOR INTEGRATED CIRCUIT PACKAGE
Our File: +015114-052310US

Dear Examiner Parekh:

Enclosed is our agenda for the interview tomorrow scheduled for 2:00 p.m. your time.

Melvin D. Chan

Original Will:	BE SENT BY MAIL	BE SENT BY FEDEX/OVERNIGHT COURIER	BE SENT BY MESSENGER	X	NOT BE SENT
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PA 3311868 v1

Outline for Interview
Application No. 09/517,345

1. Motivation to Combine

- a. Zenner - Ultra-thin package
Schueller - Standard thickness package
- b. Zenner - Flexibility after assembly
Schueller - Package flatness and coplanarity
- c. Schueller - Decouple die from substrate
Welkowsky - Directly bond die to substrate

2. Discuss combination of (1) Schueller and (2) Zenner and (3) Welkowsky

3. Discuss potential allowable claim language

- a. Examiner's suggestions
- b. Applicant's suggestions

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